

International **IR** Rectifier

RADIATION HARDENED LOGIC LEVEL POWER MOSFET SURFACE MOUNT (UB)

PD - 94764A

IRHLUB7970Z4
60V, P-CHANNEL
R⁷ TECHNOLOGY

Product Summary

Part Number	Radiation Level	R _{D(on)}	I _D
IRHLUB7970Z4	100K Rads (Si)	1.2Ω	-0.53A
IRHLUB7930Z4	300K Rads (Si)	1.2Ω	-0.53A

International Rectifier's R7™ Logic Level Power Mosfets provide simple solution to interfacing CMOS and TTL control circuits to power devices in space and other radiation environments. The threshold voltage remains within acceptable operating limits over the full operating temperature and post radiation. This is achieved while maintaining single event gate rupture and single event burnout immunity.

These devices are used in applications such as current boost low signal source in PWM, voltage comparator and operational amplifiers.



Features:

- 5V CMOS and TTL Compatible
- Fast Switching
- Single Event Effect (SEE) Hardened
- Low Total Gate Charge
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Light Weight
- Complimentary N-Channel Available - IRHLUB770Z4

Absolute Maximum Ratings

Pre-Irradiation

	Parameter	Units	
I _D @ V _{GS} = -4.5V, T _C = 25°C	Continuous Drain Current	A	-0.53
I _D @ V _{GS} = -4.5V, T _C = 100°C	Continuous Drain Current		-0.33
I _{DM}	Pulsed Drain Current ①		-2.12
P _D @ T _C = 25°C	Max. Power Dissipation	W	0.6
	Linear Derating Factor	W/C	0.0045
V _{GS}	Gate-to-Source Voltage	V	±10
E _{AS}	Single Pulse Avalanche Energy ②	mJ	3.5
I _{AR}	Avalanche Current ①	A	-0.53
E _{AR}	Repetitive Avalanche Energy ①	mJ	0.06
dv/dt	Peak Diode Recovery dv/dt ③	V/ns	-4.4
T _J	Operating Junction	°C	-55 to 150
T _{STG}	Storage Temperature Range		300 (for 5s)
	Pckg. Mounting Surface Temp.		43 (Typical)
	Weight	mg	

For footnotes refer to the last page

www.irf.com

1

04/02/04

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (Unless Otherwise Specified)

	Parameter	Min	Typ	Max	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	-60	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = -250\mu\text{A}$
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	-0.055	—	$\text{V}/^\circ\text{C}$	Reference to 25°C , $\text{I}_D = -1.0\text{mA}$
$\text{R}_{\text{DS(on)}}$	Static Drain-to-Source On-State Resistance	—	—	1.2	Ω	$\text{V}_{\text{GS}} = -4.5\text{V}, \text{I}_D = -0.33\text{A}$ ④
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	-1.0	—	-2.0	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = -250\mu\text{A}$
g_{fs}	Forward Transconductance	0.8	—	—	$\text{S} (\text{d})$	$\text{V}_{\text{DS}} = -10\text{V}, \text{I}_{\text{DS}} = -0.33\text{A}$ ④
I_{DSS}	Zero Gate Voltage Drain Current	—	—	-1.0	μA	$\text{V}_{\text{DS}} = -48\text{V}, \text{V}_{\text{GS}} = 0\text{V}$
		—	—	-10		$\text{V}_{\text{DS}} = -48\text{V}, \text{V}_{\text{GS}} = 0\text{V}, \text{T}_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Leakage Forward	—	—	-100	nA	$\text{V}_{\text{GS}} = -10\text{V}$
I_{GSS}	Gate-to-Source Leakage Reverse	—	—	100		$\text{V}_{\text{GS}} = 10\text{V}$
Q_{g}	Total Gate Charge	—	—	3.6	nC	$\text{V}_{\text{GS}} = -4.5\text{V}, \text{I}_D = -0.53\text{A}$
Q_{gs}	Gate-to-Source Charge	—	—	1.5		$\text{V}_{\text{DS}} = -30\text{V}$
Q_{gd}	Gate-to-Drain ('Miller') Charge	—	—	1.8	ns	$\text{V}_{\text{DD}} = -30\text{V}, \text{I}_D = -0.53\text{A}, \text{V}_{\text{GS}} = -4.5\text{V}, \text{R}_G = 24\Omega$
$t_{\text{d(on)}}$	Turn-On Delay Time	—	—	18		
t_{r}	Rise Time	—	—	20		
$t_{\text{d(off)}}$	Turn-Off Delay Time	—	—	15		
t_{f}	Fall Time	—	—	25	nH	Measured from the center of drain pad to center of source pad
$\text{L}_{\text{S}} + \text{L}_{\text{D}}$	Total Inductance	—	8.4	—		
C_{iss}	Input Capacitance	—	167	—	pF	$\text{V}_{\text{GS}} = 0\text{V}, \text{V}_{\text{DS}} = -25\text{V}$ $f = 1.0\text{MHz}$
C_{oss}	Output Capacitance	—	43	—		
C_{rss}	Reverse Transfer Capacitance	—	10	—		
R_{g}	Gate Resistance	—	29	—	Ω	$f = 5.1\text{MHz}$, open drain

Source-Drain Diode Ratings and Characteristics

	Parameter	Min	Typ	Max	Units	Test Conditions
I_{S}	Continuous Source Current (Body Diode)	—	—	-0.53	A	
I_{SM}	Pulse Source Current (Body Diode) ①	—	—	-2.12		
V_{SD}	Diode Forward Voltage	—	—	-5.0	V	$\text{T}_J = 25^\circ\text{C}, \text{I}_{\text{S}} = -0.53\text{A}, \text{V}_{\text{GS}} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	—	50	ns	$\text{T}_J = 25^\circ\text{C}, \text{I}_{\text{F}} = -0.53\text{A}, \text{di/dt} \leq -100\text{A}/\mu\text{s}$
Q_{RR}	Reverse Recovery Charge	—	—	25	nC	$\text{V}_{\text{DD}} \leq -25\text{V}$ ④
ton	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $\text{L}_{\text{S}} + \text{L}_{\text{D}}$.				

Thermal Resistance

	Parameter	Min	Typ	Max	Units	Test Conditions
R_{thJA}	Junction-to-Ambient	—	—	220	$^\circ\text{C}/\text{W}$	

Note: Corresponding Spice and Saber models are available on International Rectifier Web site.

For footnotes refer to the last page

Radiation Characteristics

IRHLUB7970Z4

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table 1. Electrical Characteristics @ $T_j = 25^\circ\text{C}$, Post Total Dose Irradiation^{⑤⑥}

	Parameter	100K Rads(Si) ¹		300KRads(Si) ²		Units	Test Conditions
		Min	Max	Min	Max		
BV_{DSS}	Drain-to-Source Breakdown Voltage	-60	—	-60	—	V	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = -250\mu\text{A}$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	-1.0	-2.0	-1.0	-2.0		$\text{V}_{\text{GS}} = \text{V}_{\text{DS}}, \text{I}_D = -250\mu\text{A}$
I_{GSS}	Gate-to-Source Leakage Forward	—	-100	—	-100	nA	$\text{V}_{\text{GS}} = -10\text{V}$
I_{GSS}	Gate-to-Source Leakage Reverse	—	100	—	100		$\text{V}_{\text{GS}} = 10\text{V}$
I_{DSS}	Zero Gate Voltage Drain Current	—	-1.0	—	-10	μA	$\text{V}_{\text{DS}} = -48\text{V}, \text{V}_{\text{GS}} = 0\text{V}$
$\text{R}_{\text{DS(on)}}$	Static Drain-to-Source ^④ On-State Resistance (TO-39)	—	1.2	—	1.2	Ω	$\text{V}_{\text{GS}} = -4.5\text{V}, \text{I}_D = -0.33\text{A}$
$\text{R}_{\text{DS(on)}}$	Static Drain-to-Source ^④ On-State Resistance (UB)	—	1.2	—	1.2	Ω	$\text{V}_{\text{GS}} = -4.5\text{V}, \text{I}_D = -0.33\text{A}$
V_{SD}	Diode Forward Voltage ^④	—	-5.0	—	-5.0	V	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_S = -0.53\text{A}$

1. Part number IRHLUB7970Z4

2. Part number IRHLUB7930Z4

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Single Event Effect Safe Operating Area

Ion	LET (MeV/(mg/cm ²))	Energy (MeV)	Range (μm)	VDS (V)							
				@VGS=0V	@VGS=2V	@VGS=4V	@VGS=5V	@VGS=6V	@VGS=7V	@VGS=8V	@VGS=10V
Br	37	285	36.8	-60	-60	-60	-60	-60	-50	-35	-25
I	60	345	32.7	-60	-60	-60	-60	-60	-20	-	-
Au	82	357	28.5	-60	-60	-60	-60	-	-	-	-

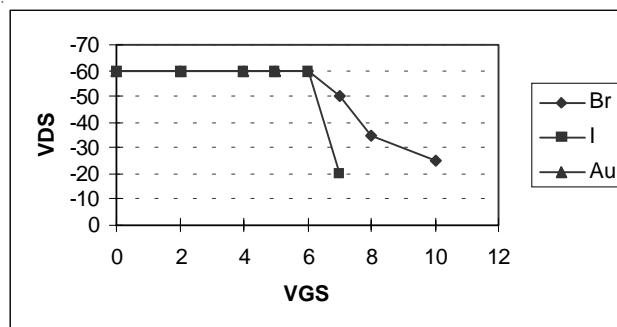


Fig a. Single Event Effect, Safe Operating Area

For footnotes refer to the last page

IRHLUB7970Z4

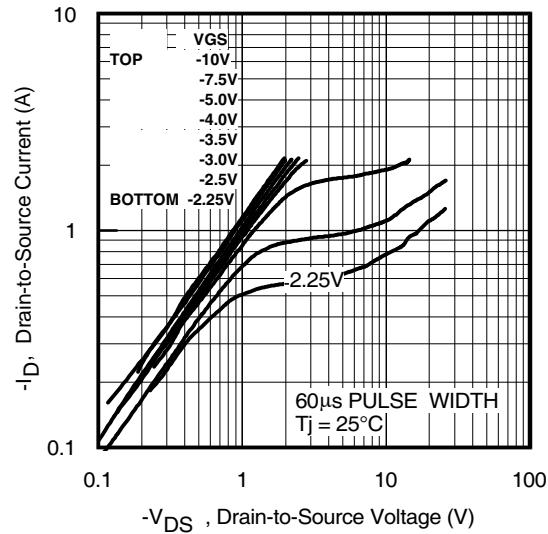


Fig 1. Typical Output Characteristics

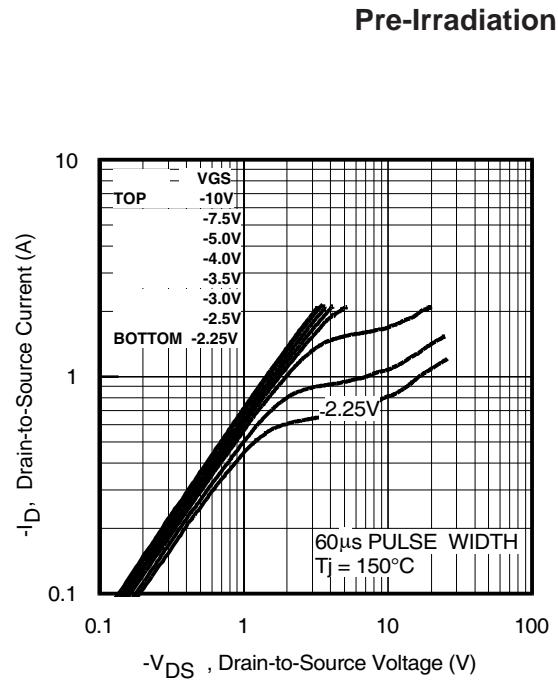


Fig 2. Typical Output Characteristics

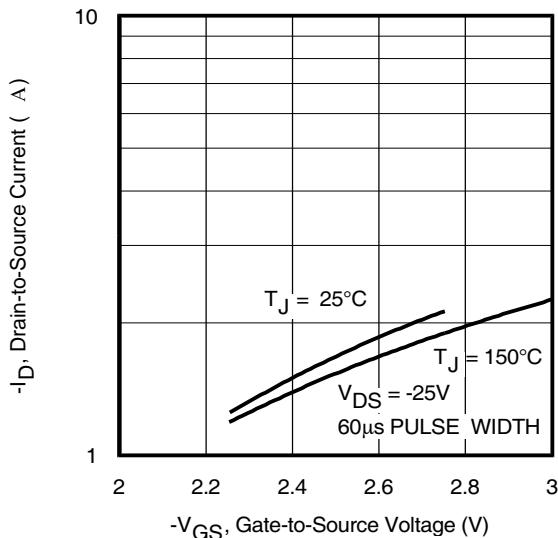


Fig 3. Typical Transfer Characteristics

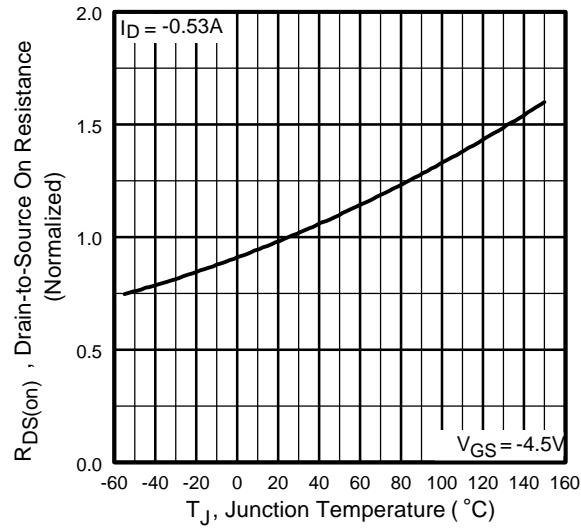


Fig 4. Normalized On-Resistance Vs. Temperature

Pre-Irradiation

IRHLUB7970Z4

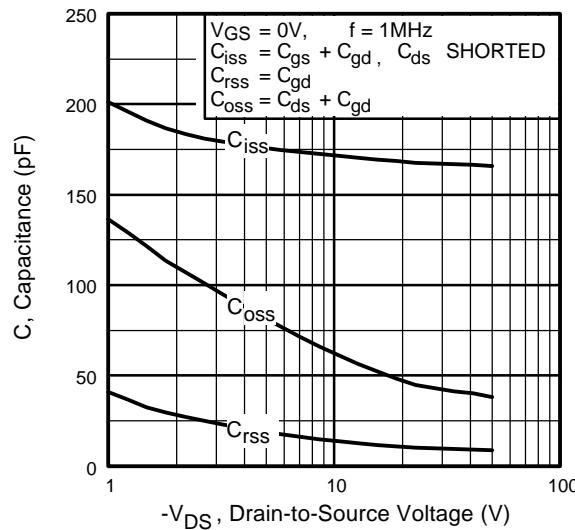


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

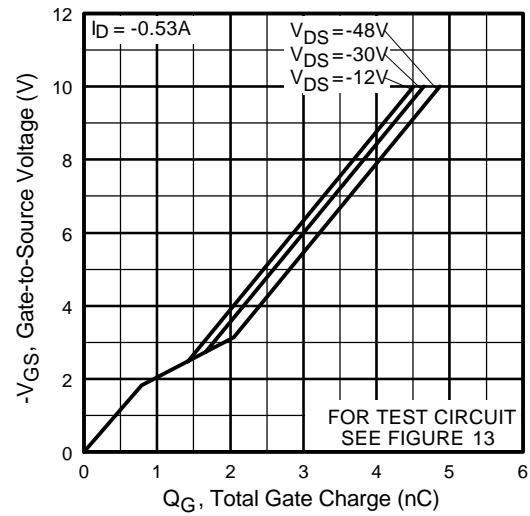


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

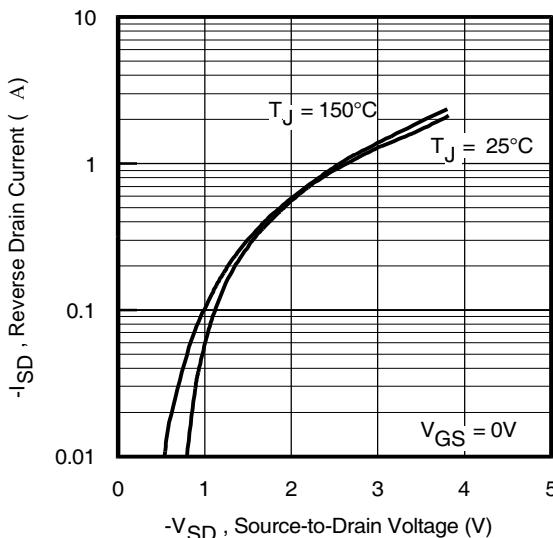


Fig 7. Typical Source-Drain Diode
Forward Voltage

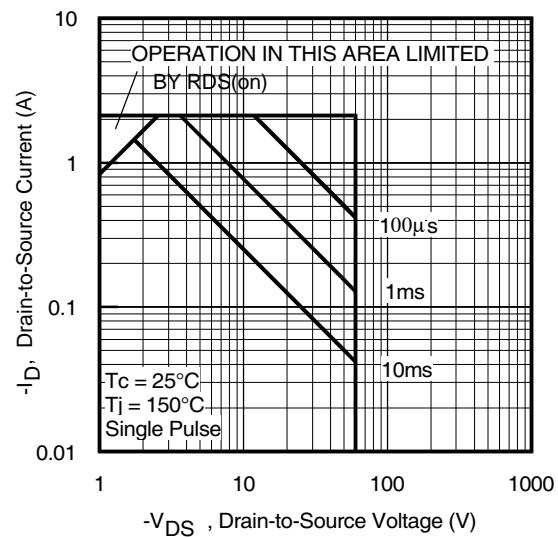


Fig 8. Maximum Safe Operating Area

IRHLUB7970Z4

Pre-Irradiation

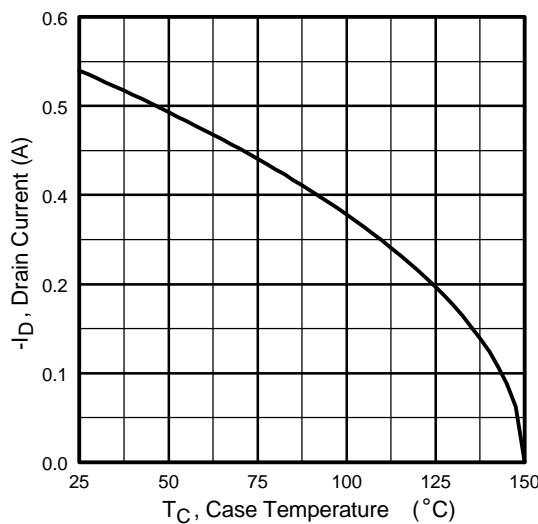


Fig 9. Maximum Drain Current Vs.
Case Temperature

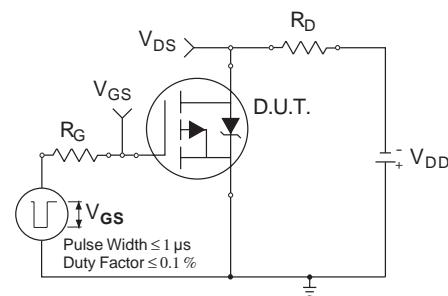


Fig 10a. Switching Time Test Circuit

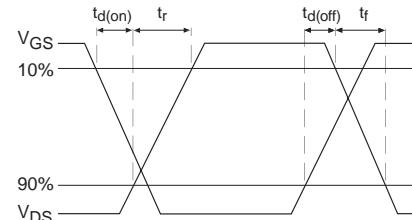


Fig 10b. Switching Time Waveforms

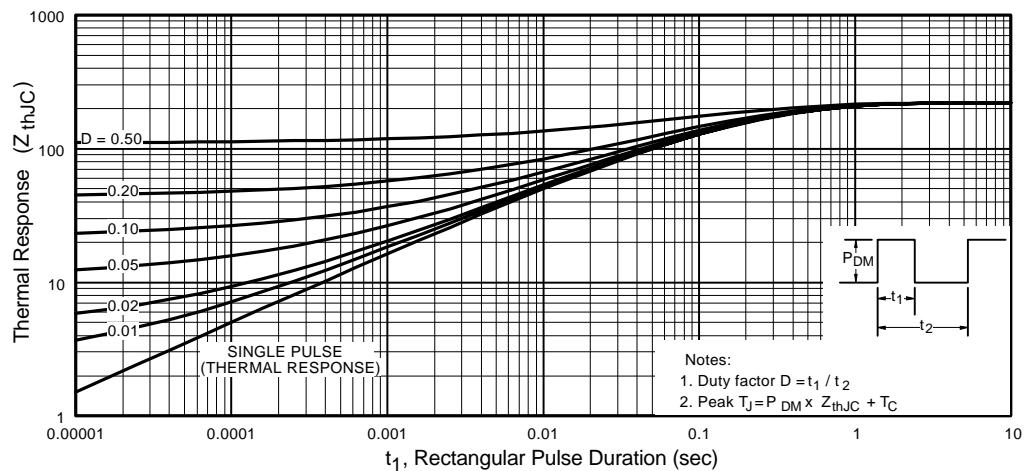


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

Pre-Irradiation

IRHLUB7970Z4

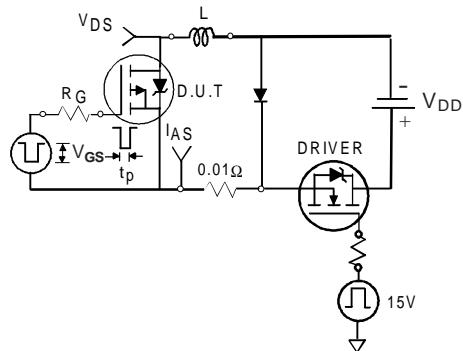


Fig 12a. Unclamped Inductive Test Circuit

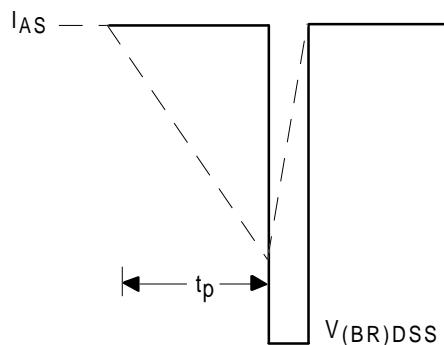


Fig 12b. Unclamped Inductive Waveforms

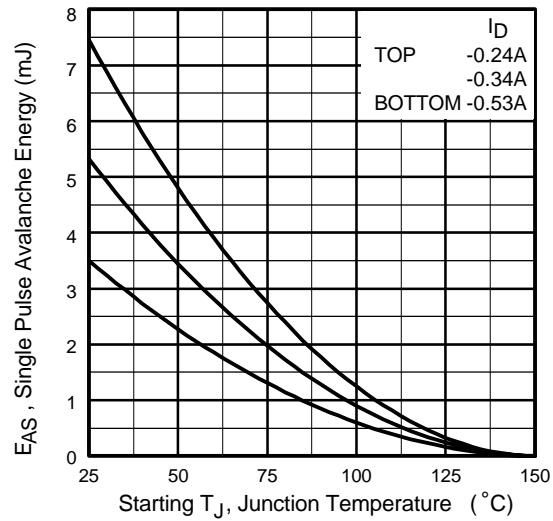


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

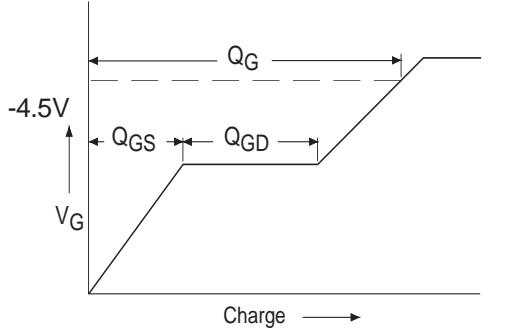


Fig 13a. Basic Gate Charge Waveform

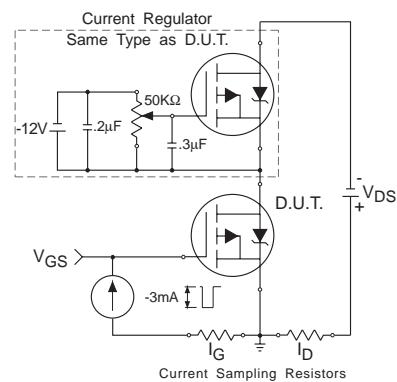
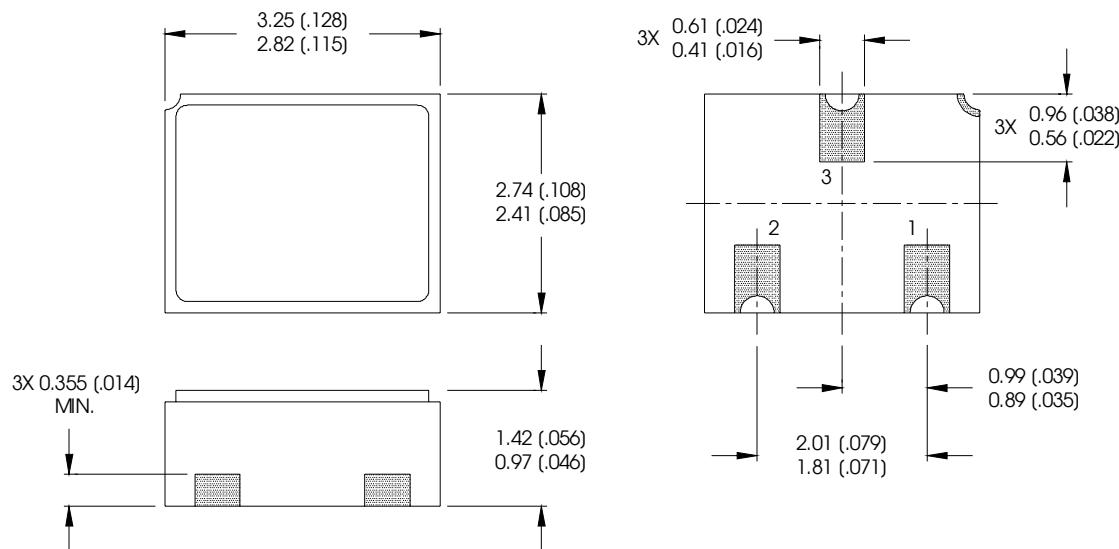


Fig 13b. Gate Charge Test Circuit

Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② $V_{DD} = -25V$, starting $T_J = 25^\circ C$, $L = 25mH$
Peak $I_L = -0.53A$, $V_{GS} = -10V$
- ③ $I_{SD} \leq -0.53A$, $dI/dt \leq -100A/\mu s$,
 $V_{DD} \leq -60V$, $T_J \leq 150^\circ C$
- ④ Pulse width $\leq 300 \mu s$; Duty Cycle $\leq 2\%$
- ⑤ **Total Dose Irradiation with V_{GS} Bias.**
-10 volt V_{GS} applied and $V_{DS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with V_{DS} Bias.**
-48 volt V_{DS} applied and $V_{GS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.

Case Outline and Dimensions — UB**NOTES:**

1. OUTLINE CONFORMS TO MIL-PRF-19500/255L
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. CONTROLLING DIMENSION: INCH.

PAD ASSIGNMENTS

- 1 = GATE
2 = SOURCE
3 = DRAIN

International
IR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105

IR LEOMINSTER : 205 Crawford St., Leominster, Massachusetts 01453, USA Tel: (978) 534-5776

TAC Fax: (310) 252-7903

Visit us at www.irf.com for sales contact information.
Data and specifications subject to change without notice. 04/2004